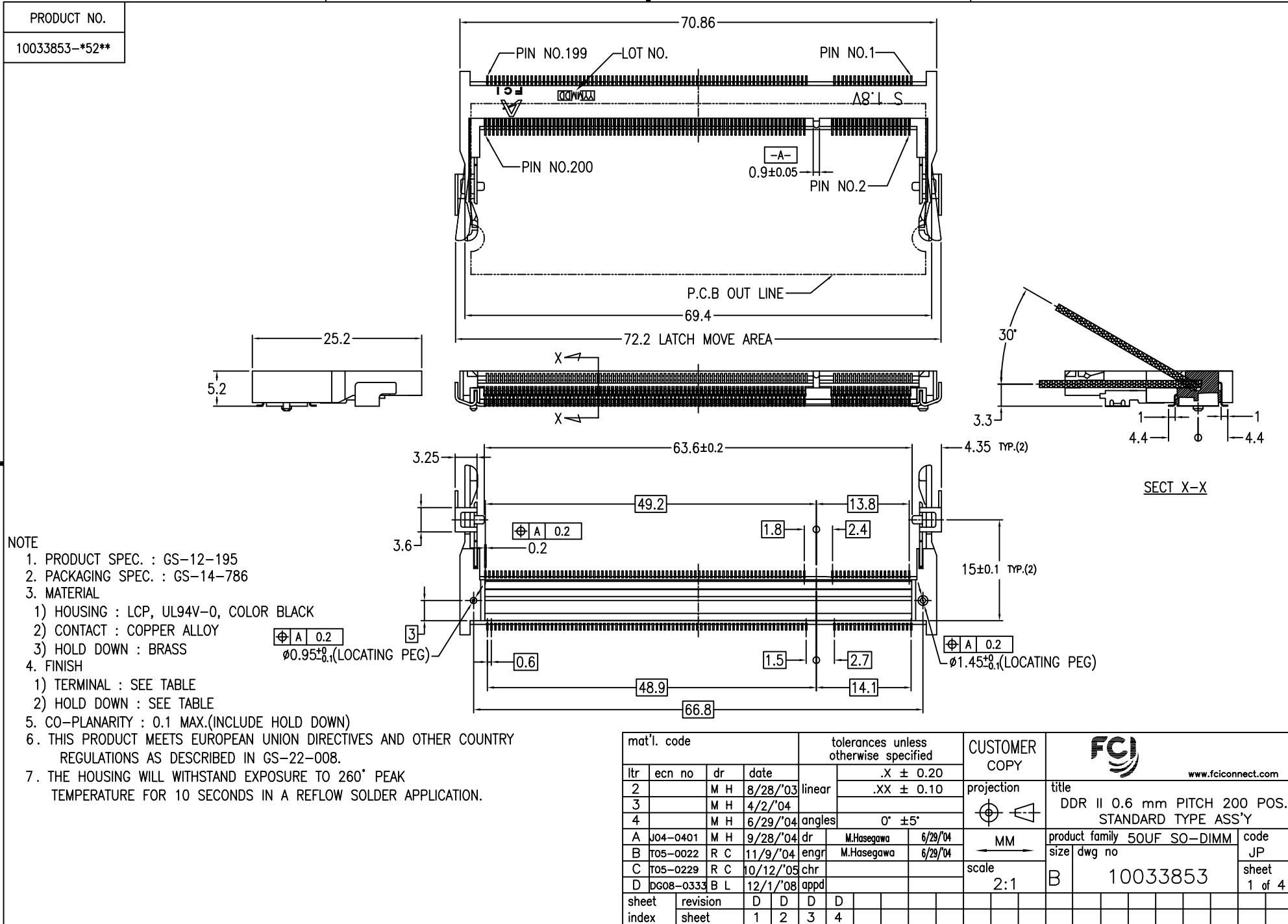
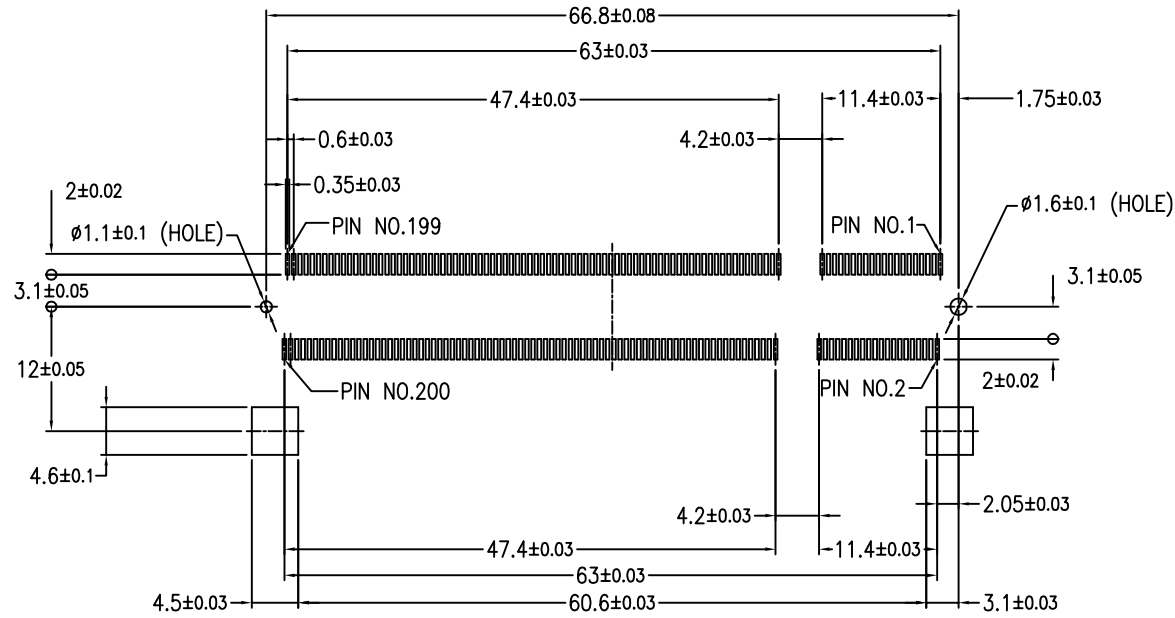




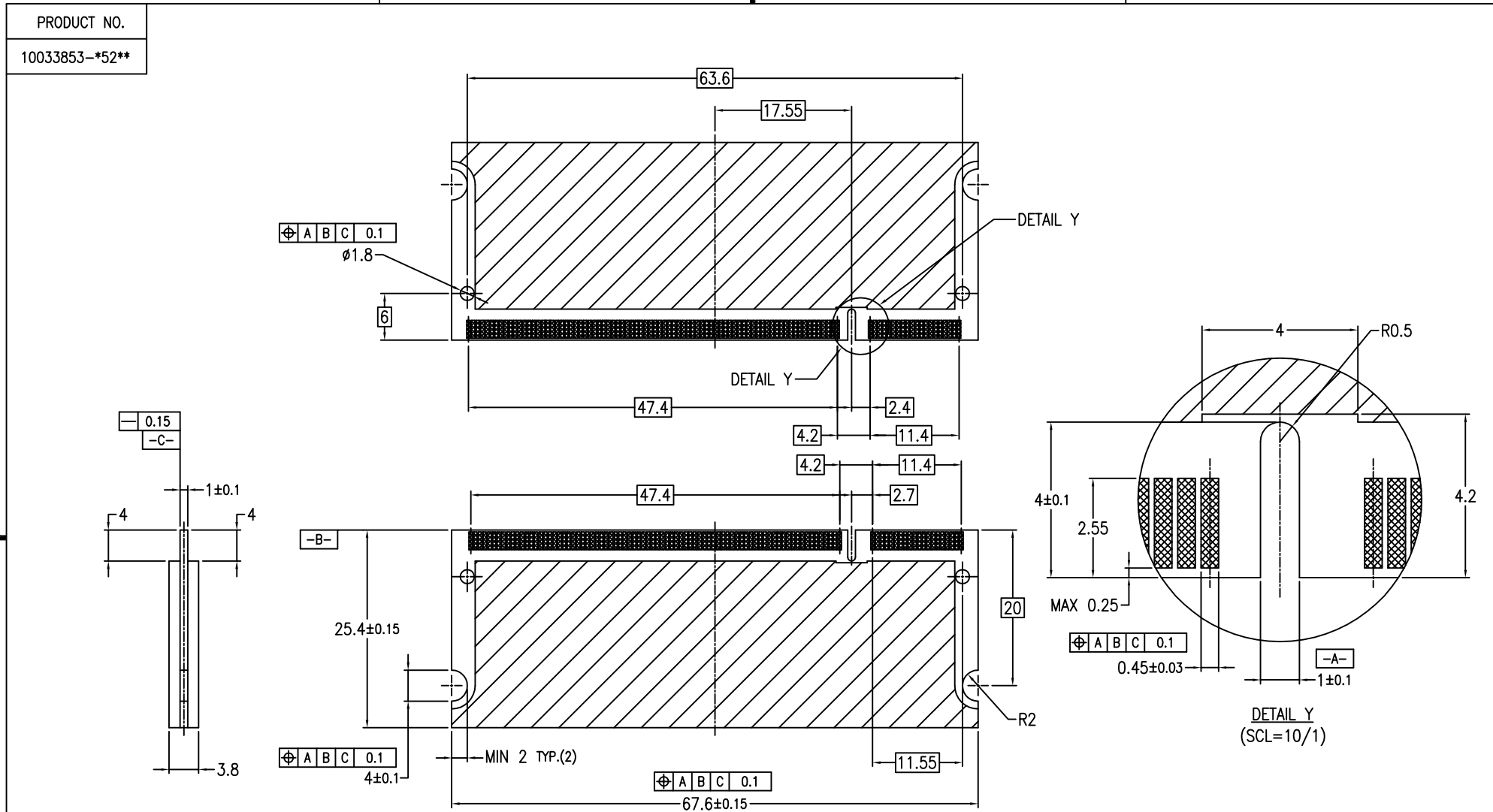


PRODUCT NO.
10033853-*52**



RECOMMENDED MOUNTING P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY	FCI			
ltr	ecn no	dr	date	linear	.X ± 0.20	.XX ± 0.10		www.fciconnect.com			
D				linear			projection	title			
				angles	0° ±5°			DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASS'Y			
				dr	M.Hasegawa	6/29/04	MM	product family 50UF SO-DIMM			code JP
				enr	M.Hasegawa	6/29/04		size dwg no			sheet 2 of
				chr			scale	B 10033853			
				appd							
sheet index	revision sheet										



RECOMMENDED MODULE P.C.B. LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	.X ± 0.20		
D				linear	.XX ± 0.10	projection	title
				angles	0° $\pm 5^\circ$		DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASS'Y
				dr	M.Hasegawa 6/29/04	MM	product family 50UF SO-DIMM
				enr	M.Hasegawa 6/29/04	scale	size dwg no
				chr		2:1	B 10033853
				appd			code JP
sheet index	revision sheet						sheet 3 of



PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033853-052FSLF	YES	Au FLASH	PURE Sn PLATING	Au FLASH
10033853-152FSLF	NO			
10033853-052TSLF	YES	Au 0.3um MIN.		
10033853-152TSLF	NO			
10033853-052ASLF	YES	Au 0.76um MIN.		
10033853-152ASLF	NO			
10033853-052FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-152FB	NO			
10033853-052TB	YES	Au 0.3um MIN.		
10033853-152TB	NO			
10033853-052AB	YES	Au 0.76um MIN.		
10033853-152AB	NO			
10033853-252FSLF	YES	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033853-352FSLF	NO			
10033853-252TSLF	YES	Au 0.3um MIN.		
10033853-352TSLF	NO			
10033853-252ASLF	YES	Au 0.76um MIN.		
10033853-352ASLF	NO			
10033853-252FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-352FB	NO			
10033853-252TB	YES	Au 0.3um MIN.		
10033853-352TB	NO			
10033853-252AB	YES	Au 0.76um MIN.		
10033853-352AB	NO			
10033853-452FS	YES	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033853-552FS	NO			
10033853-452TS	YES	Au 0.3um MIN.		
10033853-552TS	NO			
10033853-452AS	YES	Au 0.76um MIN.		
10033853-552AS	NO			
10033853-452FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-552FB	NO			
10033853-452TB	YES	Au 0.3um MIN.		
10033853-552TB	NO			
10033853-452AB	YES	Au 0.76um MIN.		
10033853-552AB	NO			

10033853-□□□□□LF

<PACKING METHOD>

R : TAPE REEL
DEFAULT : TRAY

<HOLD DOWN FINISH>

S : Pure Sn
B : Sn-Pb

<CONTACT AREA FINISH>

F : Au FLASH
T : Au 0.3um MIN.
A : Au 0.76um MIN.

<TOTAL HEIGHT>

52 : 5.2mm

<LOCATING PEG, SOLDER TAIL FINISH>

0 : YES, Au FLASH
1 : NO, Au FLASH
2 : YES, Pure Sn PLATING
3 : NO, Pure Sn PLATING
4 : YES, Sn-Pb PLATING
5 : NO, Sn-Pb PLATING

For Rohs OPTIONS:
TAIL PLATING CODE MUST BE 0~3.
HOLD DOWN PLATING CODE MUST BE "S".
"LF" CODE IS EXIST IN THE END.
EX: 10033853-252TSLF

FOR NOT Rohs COMPATIBLE:
THIS "LF" CODE IS "BLANK".
EX:10033853-452TS

mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		 www.fciconnect.com				
ltr	ecn no	dr	date	linear	.X ± 0.20			projection 	title DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASS'Y					
D					.XX ± 0.10									
				angles	0° ±5°			MM 	product family 50UF SO-DIMM					
				dr	M.Hasegawa	6/29/04	code							
				engr	M.Hasegawa	6/29/04	JP							
				chr			scale 2:1	B	dwg no 10033853				sheet 4 of	
				appd										
sheet index	revision sheet													